



Huawei Ascend 950PR

Da Vinci v3 OAM 2026

OVERVIEW

— FP32 TFLOPS	128 GB VRAM HiBL 1.0	1.6 TB/s Memory Bandwidth	900 W TDP
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PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
FP8	1000.0	8	Standard
FP4	2000.0	4	Standard
FP16	500.0	16	Standard
BF16	500.0	16	Standard

MEMORY SPECIFICATIONS

Capacity	128 GB
Type	HiBL 1.0
Bandwidth	1.6 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	900 W
Est. Max Power	1.0 kW
FP32 Efficiency	—
FP16 Efficiency	0.56 TFLOPS/W

HARDWARE DETAILS

Vendor: Huawei	Architecture: Da Vinci v3	Process Node: —
Form Factor: OAM	Launch Year: 2026	

INTERCONNECT

GPU-to-GPU: Unified Bus 2.0	Bandwidth: 2.0 TB/s
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